

January 1993 Revised August 2000

## **SCAN182373A**

# Transparent Latch with 25 $\Omega$ Series Resistor Outputs

## **General Description**

The SCAN182373A is a high performance BiCMOS transparent latch featuring separate data inputs organized into dual 9-bit bytes with byte-oriented latch enable and output enable control signals. This device is compliant with IEEE 1149.1 Standard Test Access Port and Boundary-Scan Architecture with the incorporation of the defined boundary-scan test logic and test access port consisting of Test Data Input (TDI), Test Data Out (TDO), Test Mode Select (TMS), and Test Clock (TCK).

#### **Features**

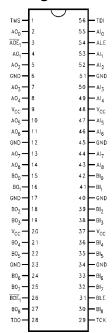
- IEEE 1149.1 (JTAG) Compliant
- High performance BiCMOS technology
- $\blacksquare$  25 $\Omega$  series resistor outputs eliminate need for external terminating resistors
- Buffered active-low latch enable
- 3-STATE outputs for bus-oriented applications
- 25 mil pitch SSOP (Shrink Small Outline Package)
- Includes CLAMP, IDCODE and HIGHZ instructions
- Additional instructions SAMPLE-IN, SAMPLE-OUT and EXTEST-OUT
- Power up 3-STATE for hot insert
- Member of Fairchild's SCAN Products

## **Ordering Code:**

Order Number	Package Number	Package Description	_
SCAN182373ASSC	MS56A	56-Lead Shrink Small Outline Package (SSOP), JEDEC MO-118, 0.300 Wide	

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code

## **Connection Diagram**



## **Pin Descriptions**

Pin Names	Description
Al <sub>(0-8)</sub> , Bl <sub>(0-8)</sub> ALE, BLE	Data Inputs
ALE, BLE	Latch Enable Inputs
$\overline{AOE}_1$ , $\overline{BOE}_1$	3-STATE Output Enable Inputs
$AO_{(0-8)}, BO_{(0-8)}$	3-STATE Latch Outputs

## **Truth Tables**

	Inputs		AO (0. 8)
ALE	†AOE <sub>1</sub>	AI (0-8)	AO (0–8)
Х	Н	Х	Z
Н	L	L	L
Н	L	Н	Н
L	L	X	$AO_0$

H = HIGH Voltage Leve	el
L = LOW Voltage Leve	ı

X = Immaterial Z = High Impedance

	BO (0. 0)		
BLE	†BOE <sub>1</sub>	BI (0-8)	BO (0-8)
Х	Н	Х	Z
Н	L	L	L
Н	L	Н	Н
L	L	Х	BO <sub>0</sub>

AO<sub>0</sub> = Previous AO before H-to-L transition of ALE

BO<sub>0</sub> = Previous BO before H-to-L transition of BLE

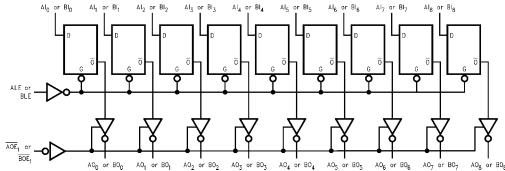
† = Inactive-to-active transition must occur to enable outputs upon power-up.

## **Functional Description**

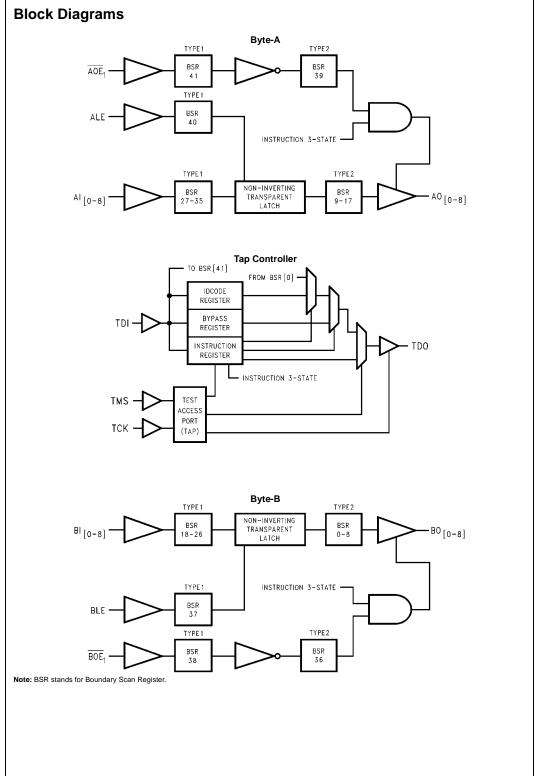
The SCAN182373A consists of two sets of nine D-type latches with 3-STATE standard outputs. When the Latch Enable (ALE or BLE) input is HIGH, data on the inputs  $(\mathsf{AI}_{(0-8)} \text{ or } \mathsf{BI}_{(0-8)})$  enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its input changes. When Latch Enable is LOW, the latches store the information that was present on

the inputs a set-up time preceding the HIGH-to-LOW transition of the Latch Enable. The 3-STATE standard outputs are controlled by the Output Enable ( $\overline{AOE}_1$  or  $\overline{BOE}_1$ ) input. When Output Enable is LOW, the standard outputs are in the 2-state mode. When Output Enable is HIGH, the standard outputs are in the high impedance mode, but this does not interfere with entering new data into the latches.

## **Logic Diagram**



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.



## **Description of BOUNDARY-SCAN Circuitry**

The scan cells used in the BOUNDARY-SCAN register are one of the following two types depending upon their location. Scan cell TYPE1 is intended to solely observe system data, while TYPE2 has the additional ability to control system data

Scan cell TYPE 1 is located on each system input pin while scan cell TYPE2 is located at each system output pin as well as at each of the two internal active-high output enable signals. AOE controls the activity of the A-outputs while BOE controls the activity of the B-outputs. Each will activate their respective outputs by loading a logic high.

The BYPASS register is a single bit shift register stage identical to scan cell TYPE1. It captures a fixed logic low.

## Bypass Register Scan Chain Definition

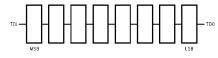


SCAN182373A Product IDCODE (32-Bit Code per IEEE 1149.1)

Version	Entity	Part	Manufacturer	Required by
		Number	ID	1149.1
0000	111111	0000001000	00000001111	1
MSB				LSB

The INSTRUCTION register is an 8-bit register which captures the default value of 10000001 (SAMPLE/PRELOAD) during the CAPTURE-IR instruction command. The benefit of capturing SAMPLE/PRELOAD as the default instruction during CAPTURE-IR is that the user is no longer required to shift in the 8-bit instruction for SAMPLE/PRELOAD. The sequence of: CAPTURE-IR  $\rightarrow$  EXIT1-IR  $\rightarrow$  UPDATE-IR will update the SAMPLE/PRELOAD instruction. For more information refer to the section on instruction definitions.

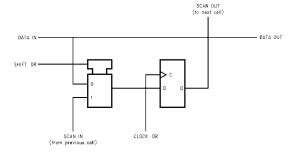
#### Instruction Register Scan Chain Definition



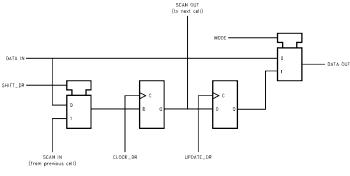
 $\text{MSB} \to \text{LSB}$ 

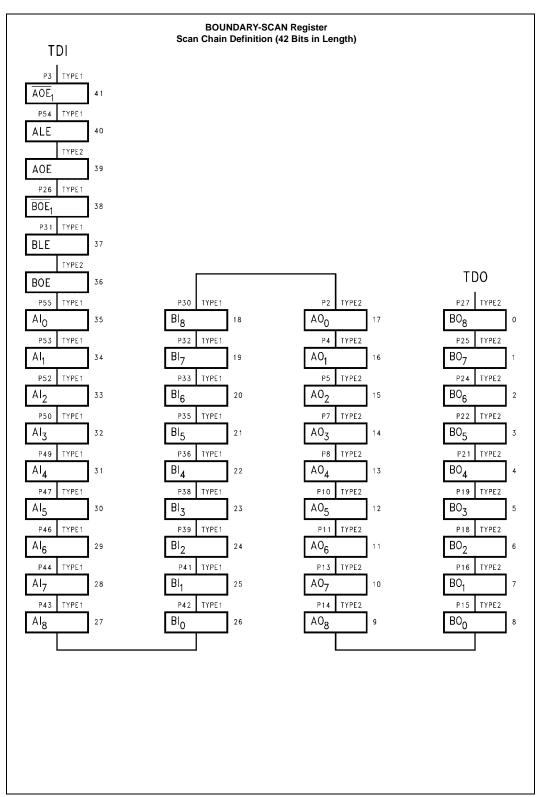
Instruction Code	Instruction
00000000	EXTEST
10000001	SAMPLE/PRELOAD
10000010	CLAMP
00000011	HIGH-Z
01000001	SAMPLE-IN
01000010	SAMPLE-OUT
00100010	EXTEST-OUT
10101010	IDCODE
11111111	BYPASS
All Others	BYPASS

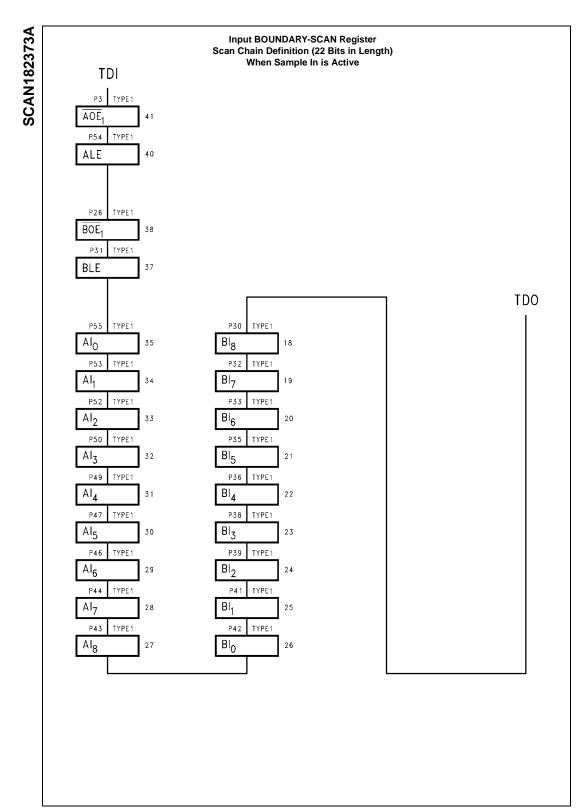
#### Scan Cell TYPE1

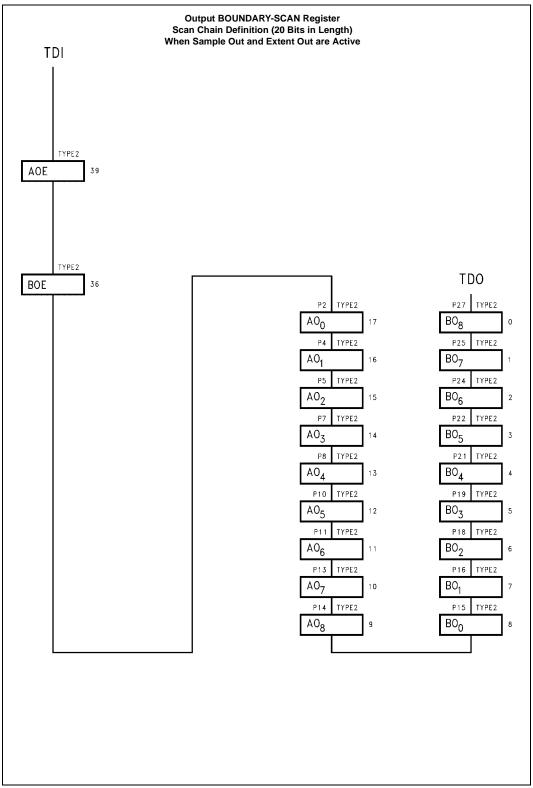


## Scan Cell TYPE2









#### **BOUNDARY-SCAN** Register Definition Index

Bit No.	Pin Name	Pin No.	Pin Type	Scan C	ell Type
41	AOE <sub>1</sub>	3	Input	TYPE1	
40	ALE	54	Input	TYPE1	
39	AOE		Internal	TYPE2	Control
38	BOE <sub>1</sub>	26	Input	TYPE1	Signals
37	BLE	31	Input	TYPE1	
36	BOE		Internal	TYPE2	
35	Al <sub>0</sub>	55	Input	TYPE1	
34	Al <sub>1</sub>	53	Input	TYPE1	
33	Al <sub>2</sub>	52	Input	TYPE1	
32	Al <sub>3</sub>	50	Input	TYPE1	
31	Al <sub>4</sub>	49	Input	TYPE1	A-in
30	Al <sub>5</sub>	47	Input	TYPE1	
29	Al <sub>6</sub>	46	Input	TYPE1	
28	Al <sub>7</sub>	44	Input	TYPE1	
27	Al <sub>8</sub>	43	Input	TYPE1	
26	BI <sub>0</sub>	42	Input	TYPE1	
25	BI <sub>1</sub>	41	Input	TYPE1	
24	BI <sub>2</sub>	39	Input	TYPE1	
23	BI <sub>3</sub>	38	Input	TYPE1	
22	BI <sub>4</sub>	36	Input	TYPE1	B-in
21	BI <sub>5</sub>	35	Input	TYPE1	
20	BI <sub>6</sub>	33	Input	TYPE1	
19	BI <sub>7</sub>	32	Input	TYPE1	
18	BI <sub>8</sub>	30	Input	TYPE1	
17	AO <sub>0</sub>	2	Output	TYPE2	
16	AO <sub>1</sub>	4	Output	TYPE2	
15	AO <sub>2</sub>	5	Output	TYPE2	
14	AO <sub>3</sub>	7	Output	TYPE2	
13	AO <sub>4</sub>	8	Output	TYPE2	A-out
12	AO <sub>5</sub>	10	Output	TYPE2	
11	AO <sub>6</sub>	11	Output	TYPE2	
10	AO <sub>7</sub>	13	Output	TYPE2	
9	AO <sub>8</sub>	14	Output	TYPE2	
8	BO <sub>0</sub>	15	Output	TYPE2	
7	BO <sub>1</sub>	16	Output	TYPE2	
6	BO <sub>2</sub>	18	Output	TYPE2	
5	BO <sub>3</sub>	19	Output	TYPE2	
4	BO <sub>4</sub>	21	Output	TYPE2	B-out
3	BO <sub>5</sub>	22	Output	TYPE2	
2	BO <sub>6</sub>	24	Output	TYPE2	
1	BO <sub>7</sub>	25	Output	TYPE2	
0	BO <sub>8</sub>	27	Output	TYPE2	

## Absolute Maximum Ratings(Note 1)

 $\begin{array}{ll} \mbox{Storage Temperature} & -65\mbox{°C to } +150\mbox{°C} \\ \mbox{Ambient Temperature under Bias} & -55\mbox{°C to } +125\mbox{°C} \\ \end{array}$ 

Voltage Applied to Any Output

in Disabled or Power-Off State -0.5 V to +5.5 V in the HIGH State  $-0.5 \text{V to } \text{V}_{\text{CC}}$ 

Current Applied to Output

in LOW State (Max) Twice the Rated  $I_{OL}$  (mA) DC Latchup Source Current -500 mA Over Voltage Latchup (I/O) 10V

ESD (HBM) Min 2000V

# Recommended Operating Conditions

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit of current limit is sufficient to protect inputs.

#### **DC Electrical Characteristics**

Symbol	•		v <sub>cc</sub>	Min	Тур	Max	Units	Conditions	
V <sub>IH</sub>				2.0			V	Recognized HIGH Signal	
V <sub>IL</sub>	Input LOW Voltage					0.8	V	Recognized LOW Signal	
V <sub>CD</sub>	Input Clamp Diode Volta	age Output	Min			-1.2	V	I <sub>IN</sub> = -18 mA	
V <sub>OH</sub>	HIGH Voltage		Min	2.5			V	$I_{OH} = -3 \text{ mA}$	
			Min	2.0			V	I <sub>OH</sub> = -32 mA	
V <sub>OL</sub>	Input HIGH Voltage Input LOW Voltage Input Clamp Diode Voltage Output HIGH Voltage Output LOW Voltage Input HIGH Current All Others Input HIGH Current Breakdown Test Input HIGH Current Breakdown Test (I/O) Input LOW Current All Others TMS, TDI Input LOW Current TMS, TDI Input LOW Current Output Leakage Test Output Leakage Current Output Leakage Current Output Leakage Current		Min			0.8	V	I <sub>OL</sub> = 15 mA	
I <sub>IH</sub>	Input HIGH Current	All Others	Max			5	μΑ	V <sub>IN</sub> = 2.7V (Note 3)	
V <sub>IH</sub> V <sub>IL</sub> V <sub>ID</sub> VOH  VOL I <sub>IH</sub> I <sub>BVI</sub> I <sub>IL</sub> I <sub></sub>			Max			5	μΑ	$V_{IN} = V_{CC}$	
		TMS, TDI	Max			5	μΑ	$V_{IN} = V_{CC}$	
BVI	Input HIGH Current Bre	akdown Test	Max			7	μΑ	V <sub>IN</sub> = 7.0V	
BVIT			Max			100	μΑ	V <sub>IN</sub> = 5.5V	
IL	Input LOW Current	All Others	Max			-5	μΑ	V <sub>IN</sub> = 0.5V (Note 3)	
			Max			-5	μΑ	V <sub>IN</sub> = 0.0V	
		TMS, TDI	Max			-385	μΑ	V <sub>IN</sub> = 0.0V	
V <sub>ID</sub>	Input Leakage Test		0.0	4.75			V	$I_{ID} = 1.9 \mu A$	
								All Other Pins Grounded	
I <sub>IH</sub> + I <sub>OZH</sub>	Output Leakage Current Output Leakage Current Output Leakage Current Output Short-Circuit Current		Max			50	μΑ	V <sub>OUT</sub> = 2.7V	
I <sub>IL</sub> + L <sub>OZL</sub>			Max			-50		V <sub>OUT</sub> = 0.5V	
OZH			Max			50	μΑ	V <sub>OUT</sub> = 2.7V	
OZL			Max			-50	μΑ	V <sub>OUT</sub> = 0.5V	
os			Max	-100		-275	mA	V <sub>OUT</sub> = 0.0V	
CEX	Output HIGH Leakage Current		Max			50	μА	$V_{OUT} = V_{CC}$	
ZZ	Output HIGH Leakage Current Bus Drainage Test		0.0			100	μΑ	V <sub>OUT</sub> = 5.5V	
IOZH Output Leakage Current IOZL Output Leakage Current IOS Output Short-Circuit Curr ICEX Output HIGH Leakage C IZZ Bus Drainage Test ICCH Power Supply Current ICCL Power Supply Current								All Others Grounded	
ссн	Power Supply Current		Max			250	μА	$V_{OUT} = V_{CC}$ ; TDI, TMS = $V_{CC}$	
			Max			1.0	mA	$V_{OUT} = V_{CC}$ ; TDI, TMS = GND	
CCL	Power Supply Current		Max			65	mA	$V_{OUT} = LOW$ ; TDI, TMS = $V_{CC}$	
			Max			65.8	mA	V <sub>OUT</sub> = LOW; TDI, TMS = GND	
CCZ	Power Supply Current		Max			250	μΑ	TDI, TMS = V <sub>CC</sub>	
			Max			1.0	mA	TDI, TMS = GND	
ССТ	Additional I <sub>CC</sub> /Input	All Other Inputs	Max			2.9	mA	$V_{IN} = V_{CC} - 2.1V$	
		TDI, TMS Inputs	Max			3	mA	$V_{IN} = V_{CC} - 2.1V$	
CCD	Dynamic I <sub>CC</sub>	No Load	Max			0.2	mA/	Outputs Open	
							MHz	One Bit Toggling, 50% Duty Cycle	

## **AC Electrical Characteristics**

Normal Operation:

		v <sub>cc</sub>	T <sub>A</sub>	=-40°C to +85	5°C	
Symbol	Parameter	(V)		$\textbf{C}_{\textbf{L}} = \textbf{50 pF}$		Units
		(Note 4)	Min	Тур	Max	
t <sub>PLH</sub>	Propagation Delay	5.0	1.2	3.7	6.5	20
t <sub>PHL</sub>	D to Q		2.0	4.5	7.4	ns
t <sub>PLH</sub>	Propagation Delay	5.0	1.3	4.1	7.4	ns
t <sub>PHL</sub>	LE to Q		1.8	4.5	7.3	115
t <sub>PLZ</sub>	Disable Time	5.0	1.6	4.9	9.0	ns
t <sub>PHZ</sub>			1.8	6.0	10.7	115
t <sub>PZL</sub>	Enable Time	5.0	1.6	6.0	9.5	ns
t <sub>PZH</sub>			1.0	5.0	9.3	115

Note 4: Voltage Range 5.0V ± 0.5V

# **AC Operating Requirements**

Normal Operation:

Symbol	Parameter	V <sub>CC</sub> (V) (Note 5)	$T_A = -40$ °C to +85°C $C_L = 50$ pF Guaranteed Minimum	Units
t <sub>S</sub>	Setup Time, H or L Data to LE	5.0	1.7	ns
t <sub>H</sub>	Hold Time, H or L LE to Data	5.0	1.6	ns
t <sub>W</sub>	LE Pulse Width	5.0	2.3	ns

Note 5: Voltage Range 5.0V ±0.5V

# **AC Electrical Characteristics**

Scan Test Operation:

		V <sub>CC</sub>	T <sub>A</sub>			
Symbol	Parameter	(V)		$\textbf{C}_{\boldsymbol{L}} = \textbf{50 pF}$		Units
		(Note 6)	Min Typ		Max	
PLH	Propagation Delay	5.0	3.6	5.8	8.6	ns
PHL	TCK to TDO		4.8	7.4	10.6	113
PLZ	Disable Time	5.0	2.7	5.6	9.0	no
t <sub>PHZ</sub>	TCK to TDO		4.0	7.1	10.9	ns
t <sub>PZL</sub>	Enable Time	5.0	5.2	8.6	12.5	ns
t <sub>PZH</sub>	TCK to TDO		3.6	6.6	10.1	115
t <sub>PLH</sub>	Propagation Delay		3.9	6.4	9.5	ns
t <sub>PHL</sub>	TCK to Data Out during Update-DR State	5.0	5.1	8.0	11.6	115
t <sub>PLH</sub>	Propagation Delay		4.7	7.7	11.3	no
t <sub>PHL</sub>	TCK to Data Out during Update-IR State	5.0	5.7	9.1	13.1	ns
t <sub>PLH</sub>	Propagation Delay	5.0	5.5	9.2	13.6	20
t <sub>PHL</sub>	TCK to Data Out during Test Logic Reset State		6.7	10.7	15.6	ns
t <sub>PLZ</sub>	Disable Time		4.1	7.7	12.1	ns
t <sub>PHZ</sub>	TCK to Data Out during Update-DR State	5.0	4.7	8.4	12.7	115
t <sub>PLZ</sub>	Disable Time		4.2	8.3	13.5	
t <sub>PHZ</sub>	TCK to Data Out during Update-IR State	5.0	4.7	9.0	14.0	ns
t <sub>PLZ</sub>	Disable Time	5.0	5.5	10.1	15.6	
t <sub>PHZ</sub>	TCK to Data Out during Test Logic Reset State		6.3	10.8	16.2	ns
t <sub>PZL</sub>	Enable Time		5.8	9.6	14.2	
t <sub>PZH</sub>	TCK to Data Out during Update-DR State	5.0	4.3	7.7	11.7	ns
t <sub>PZL</sub>	Enable Time		6.1	11.0	16.0	
t <sub>PZH</sub>	TCK to Data Out during Update-IR State	5.0	4.7	9.0	13.7	ns
t <sub>PZL</sub>	Enable Time	5.0	7.3	12.5	18.3	n=
t <sub>PZH</sub>	TCK to Data Out during Test Logic Reset State		5.8	10.5	15.8	ns

# **AC Operating Requirements**

Scan Test Operation:

Symbol	Parameter	V <sub>CC</sub> (V) (Note 7)	$T_A = -40^{\circ}C$ to $+85^{\circ}C$ $C_L = 50$ pF  Guaranteed Minimum	Units
Data to TCK (Note 8)	5.0	2.7	ns	
t <sub>H</sub>	Hold Time,	5.0	2.4	ns
	Data to TCK (Note 8)			
t <sub>S</sub>	Setup Time, H or L	5.0	5.1	ns
	AOE 1, BOE 1 to TCK (Note 9)			
t <sub>H</sub>	Hold Time, H or L	5.0	1.8	ns
	TCK to AOE 1, BOE 1 (Note 9)			
t <sub>S</sub>	Setup Time, H or L	5.0	3.5	ns
	Internal AOE, BOE, to TCK (Note 10)			
t <sub>H</sub>	Hold Time, H or L	5.0	1.8	ns
	TCK to Internal			
	AOE, BOE (Note 10)			
t <sub>S</sub>	Setup Time	5.0	5.1	ns
	ALE, BLE (Note 11) to TCK			
t <sub>H</sub>	Hold Time	5.0	1.8	ns
	TCK to ALE, BLE (Note 11)			
t <sub>S</sub>	Setup Time, H or L	5.0	7.9	ns
	TMS to TCK			
t <sub>H</sub>	Hold Time, H or L	5.0	1.8	ns
	TCK to TMS			
t <sub>S</sub>	Setup Time, H or L	5.0	6.0	ns
	TDI to TCK			
t <sub>H</sub>	Hold Time, H or L	5.0	3.0	ns
	TCK to TDI	3.0	3.0	115
t <sub>W</sub>	Pulse Width TCK H	5.0	10.3	ns
	L		10.3	115
f <sub>MAX</sub>	Maximum TCK Clock Frequency	5.0	50	MHz
t <sub>PU</sub>	Wait Time, Power Up to TCK	5.0	100	ns
t <sub>DN</sub>	Power Down Delay	0.0	100	ms

Note 7: Voltage Range 5.0V ± 0.5V.

Note 8: This delay represents the timing relationship between the data input and TCK at the associated scan cells numbered 0-8, 9-17, 18-26 and 27-35.

Note 9: Timing pertains to BSR 38 and 41 only.

Note 10: This delay represents the timing relationship between AOE/BOE and TCK for scan cells 36 and 39 only.

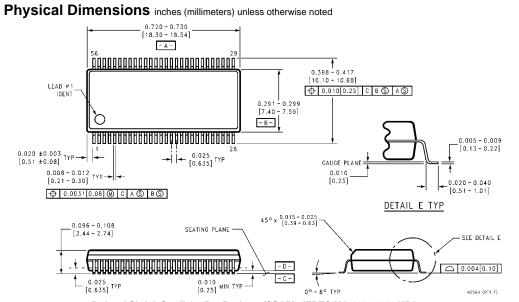
Note 11: Timing pertains to BSR 37 and 40 only.

 $\textbf{Note:} \ \textbf{All Input Timing Delays involving TCK} \ are \ measured \ from \ the \ rising \ edge \ of \ TCK.$ 

## Capacitance

Symbol	Parameter	Тур	Units	Conditions, T <sub>A</sub> = 25°C
C <sub>IN</sub>	Input Capacitance	5.8	pF	V <sub>CC</sub> = 0.0V
C <sub>OUT</sub>	Output Capacitance (Note 12)	13.8	pF	V <sub>CC</sub> = 5.0V

Note 12: C<sub>OUT</sub> is measured at frequency f = 1 MHz, per MIL-STD-883B, Method 3012



56-Lead Shrink Small Outline Package (SSOP), JEDEC MO-118, 0.300 Wide Package Number MS56A

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